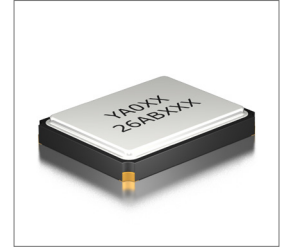


**Features**

- $\pm 0.5$ ppm (Frequency Stability)
- Clipped Sinewave
- TCXO
- Tape and Reel
- Analog Compensation

**Applications**

- GPS Application


**Part Numbering Guide**

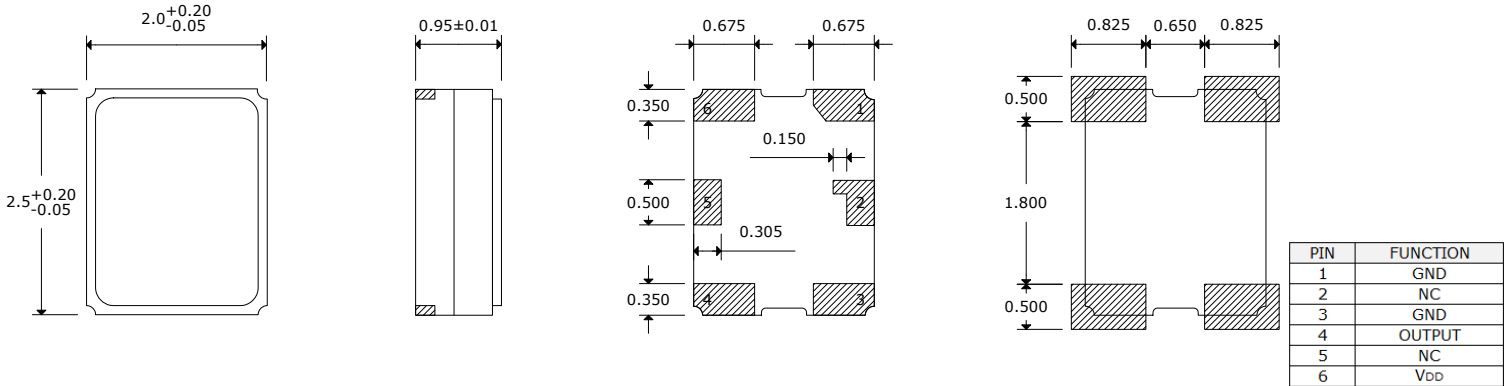
**STX488-26.000MHz**



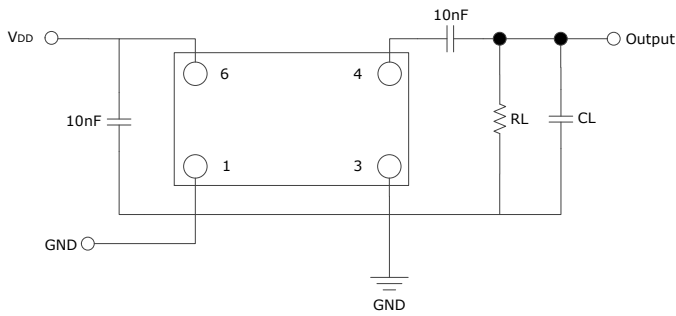
Electrical Parameters	Units	Minimum	Typical	Maximum	Remarks
Frequency Range	MHz		26.000		
Frequency Tolerance at +25°C	ppm	-2.0		2.0	After 2 times reflow
Freq. Stability vs. Op Temp.	ppm	-0.5		0.5	Reference to frequency at 25°C
Freq. Stability vs. Supply Voltage	ppm	-0.1		0.1	V <sub>DD</sub> ±5% change.
Freq. Stability vs. Load	ppm	-0.1		0.1	±10% change
Freq. Stability vs. Aging 1 year	ppm	-0.7		0.7	
Freq. Stability vs. Aging 2 years	ppm	-1.4		1.4	
Freq. Stability vs. Aging 5 years	ppm	-2.5		2.5	
Freq. Stability vs. Aging 10 years	ppm	-5.0		5.0	
Operating Temperature	°C	-30		85	
Storage Temperature	°C	-40		85	
Operating Voltage (V <sub>DD</sub> )	V	1.8	2.8	3.0	±5%
Current (I <sub>DD</sub> )	mA			1.5	
Output Load (Clipped Sinewave)	kΩ/pF		10/10		±10%
Output Logic Levels	V <sub>P-P</sub>	0.8			
Symmetry (Duty Cycle)	%	45	50	55	
Harmonics	dBc			-8	
Start-Up Time	ms			2	
Phase Noise (Typical) 1Hz Offset	dBc/Hz			-50	
Phase Noise (Typical) 5Hz Offset	dBc/Hz			-73	
Phase Noise (Typical) 10Hz Offset	dBc/Hz			-85	
Phase Noise (Typical) 100Hz Offset	dBc/Hz			-110	
Phase Noise (Typical) 1KHz Offset	dBc/Hz			-134	
Phase Noise (Typical) 10KHz Offset	dBc/Hz			-144	
Phase Noise (Typical) 100KHz Offset	dBc/Hz			-152	

**Outline Drawing**

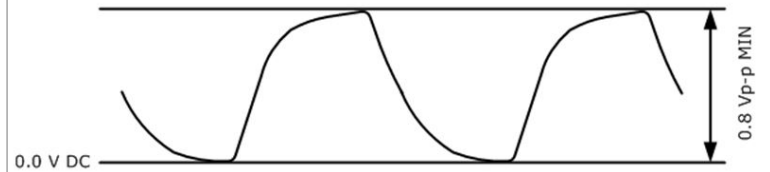
All dimensions are in millimeters (mm) unless otherwise noted. Drawings are not to scale.



**Test Circuit (Clipped Sinewave)**



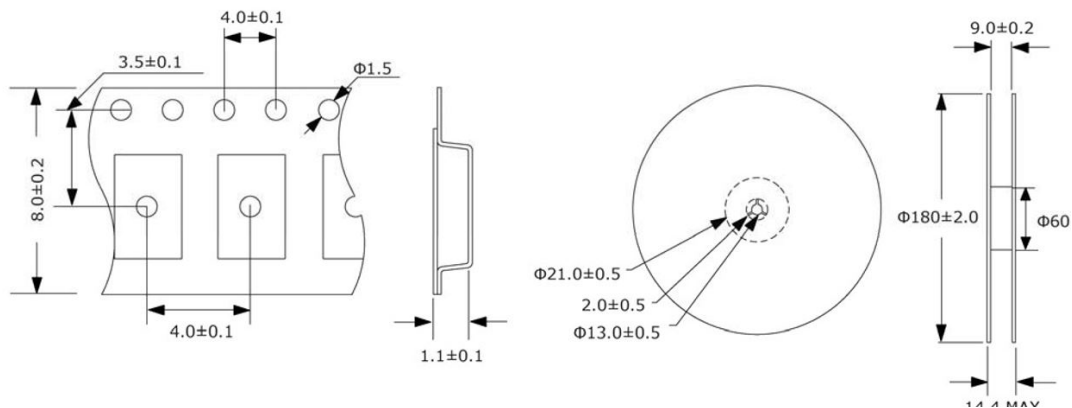
**Waveform (Clipped Sinewave)**



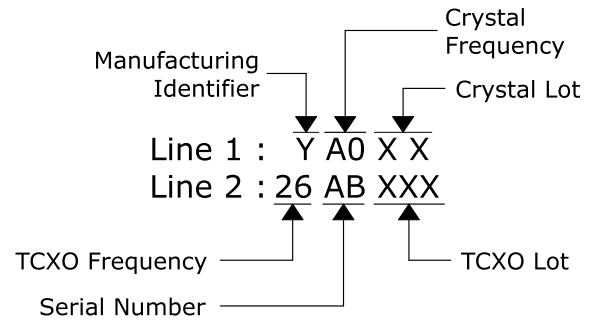
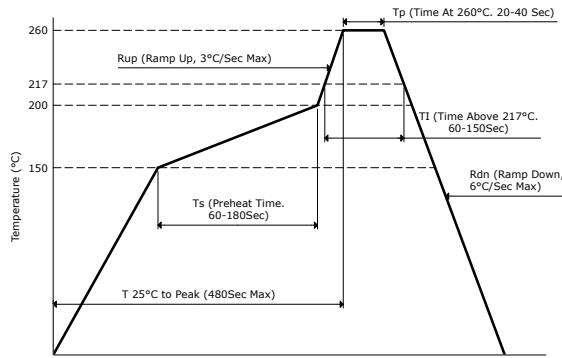
**Tape And Reel Dimensions**

All dimensions are in millimeters (mm) unless otherwise noted. Drawings are not to scale.

3,000pcs/Reel



**Reflow Profile & Part Marking**



**Environmental Specifications**

Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Solderability	MIL-STD-883, Method 2003
Moisture Sensitivity	J-STD-020, MSL 1

**Mechanical Specifications**

Mechanical Shock	MIL-STD-202, Method 213, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A
Moisture Resistance	MIL-STD-883, Method 1004
Resistance to Solvents	MIL-STD-202, Method 215
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K